NCCAVS – CMPUG Meeting
www.avsusergroups.org

Topic: *Advances in CMP Consumables, Materials, and Tools*

Meeting Date: April 12, 2018

Time: 1:00 - 6:00 p.m. *(badge pick up @ 12:30 p.m.)*

Location: Nanofab South Auditorium
SUNY Polytechnic Institute
College of NanoScale Science & Engineering (CNSE)
University at Albany
255 Fuller Road
Albany, NY 12203

Parking: FREE! Follow the event parking sign (to be posted by the security prior to the event).

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FREE ONLINE REGISTRATION*:

NEED TO REGISTER IN ADVANCE FOR SECURITY APPROVAL!
ONLINE REGISTRATION

**You will need to bring your passport if you are not a U.S. Citizen*

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CO-CHAIRS

Michael Pevny, 3M Company, mpevny@mmm.com
Dinesh Koli, GlobalFoundries, dinesh.koli@globalfoundries.com

SPEAKERS/AGENDA

12:30 pm Registration/Badge Pick up at the security desk.

12:50 pm Welcome and Acknowledgment of sponsors by Michael Pevny, 3M and Dinesh Koli, GlobalFoundries

1:00 pm Outlook for CMP Consumables, Mike Corbett, Linx Consulting

1:20pm Recent Trend of CMP Equipment Platform and its Requirement of Process and Consumables: BEOL CMP, Sunghoon Lee, GlobalFoundries

1:40 pm Particle Developments as an Enabler of Next Generation Ceria Slurries, Nate Urban, Ferro

2:00 pm Almost Complete Removal of sub-90nm Ceria Particles from Silicon Dioxide Surfaces, Jihoon Seo, Clarkson University

2:15 pm Studying Effects of Surfactants on CMP Slurries with Holographic Characterization, Fook Chiong Cheong, Spheryx Inc.

2:35 pm Reduced Cost of Ownership Oxide CMP Process using 300mm Consumables for 200mm Processing, Christopher Eric Brannon, Texas Instruments

2:55 pm 3D Trajectories, Diffusion, and Interaction Energies of Ceria Particles on Glass Surfaces, Akshay Gowda, Clarkson University

3:10 pm Coffee Break - Networking

3:40 pm High Efficiency Post-CMP Cleans for Advanced FEOL and MOL Applications, Paul Bernatis, Dupont-EKC Technology

4:00 pm Tuning Wear Rate and Surface Finish of CMP Pads via Precise Control of Pad Conditioner Features, Matthew Fritz, 3M Company

4:20pm Tribocorrosion Mechanism for Tungsten Void in CMP *in-situ* Cleaning, Hong Jin Kim, Global Foundries

4:40 pm Assay Characterization of Industrial CMP Slurries Based on Densitometry, Refractive Index and Dynamic Light Scattering, Leticia Vázquez Bengochea, University of Arizona

4:55 pm Advanced Cu CMP Slurries for Advances Node Cu CMP Applications, Tom Shi, Versum Materials

5:15 pm Cobalt Buff Step CMP for Middle of the Line Applications and Reduction in Slurry Consumption Using a Novel Slurry Injection System, Calliandra Stuffle, University of Arizona

5:30 pm ICPT Announcement and concluding remarks by Michael Pevny, 3M and Dinesh Koli, GlobalFoundries

5:40 pm Meeting adjourn

6:00 pm Gratis Dinner served following the conclusion of the talks just outside of the meeting room.

All presentations will be requested to be posted on the CMPUG Proceedings webpage approximately 1-2 weeks following the meeting.

If you would like to sponsor a user group meeting please check out the
NCCAVS User Groups Marketing Opportunities